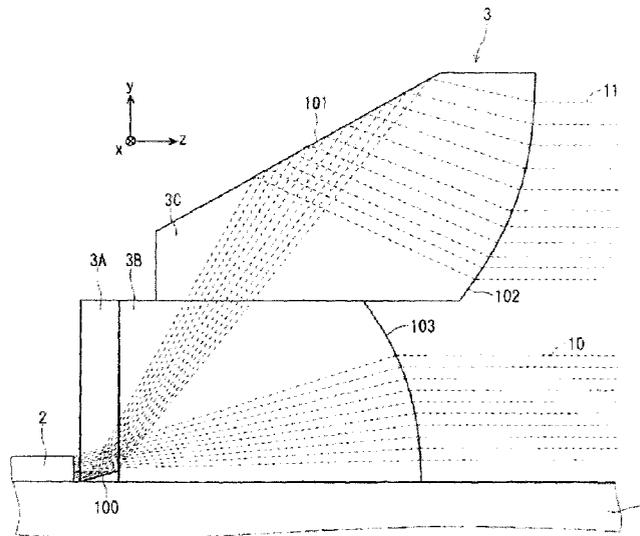




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(54) Titre : DISPOSITIF DE SOURCE DE LUMIERE LASER ET PROCEDE DE FABRICATION DE DISPOSITIF DE SOURCE DE LUMIERE LASER  
(54) Title: LASER LIGHT SOURCE DEVICE AND METHOD FOR MANUFACTURING LASER LIGHT SOURCE DEVICE



(57) **Abrégé/Abstract:**

The art disclosed in the present description relates to: a laser light source device capable of suppressing a loss of light output from a semiconductor laser element, while ensuring the degree of freedom in disposition of a semiconductor laser element; and a method for manufacturing the laser light source device. A laser light source device relating to the present art is provided with a semiconductor laser element (2), and an optical element (3) that is provided on the optical axis of output light outputted from the semiconductor laser element (2). The optical element (3) separates, in the fast axis direction, a part of a luminous flux of the output light from the other part of the luminous flux, said output light having been outputted from the semiconductor laser element (2), and not having been separated in the fast axis direction.

## ABSTRACT

A technology disclosed in the specification of the subject application relates to a laser light source device capable of suppressing loss of optical output power from a semiconductor laser device, and to a method of manufacturing of a laser light source device while the degree of freedom in arrangement of the semiconductor laser device is secured. A laser light source device according to the subject technology includes a semiconductor laser device (2), and an optical element (3) provided on an optical axis of an emission light emitted from the semiconductor laser device (2). The optical element (3) separates a portion of a luminous flux of an emission light that is emitted from the semiconductor laser device (2) and that is not separated in a fast axis direction from another portion so as to be separated in the fast axis direction.

LASER LIGHT SOURCE DEVICE AND METHOD OF MANUFACTURING LASER  
LIGHT SOURCE DEVICE

Technical Field

5 [0001] A technology disclosed in the specification of the subject application relates to a laser light source device including a semiconductor laser device and to a method of manufacturing a laser light source device including a semiconductor laser device, for example.

10 Background Art

[0002] As a light source included in a display device such as a projector, a light source using a halogen lamp or a metal halide lamp is used. However, in recent years, a laser light source having the features of long life, low power consumption, high luminance, and high color purity has been actively applied to a display device.

15 [0003] An optical device used in digital cinema or the like, such as a large-size projector, enhances its output power by increasing the number of installed laser light sources in order to obtain required optical output power. However, such increase in the number of installed laser light sources involves generation of disadvantages of increase in the size of the device and also increase in costs. Accordingly, enhancement of optical  
20 output power in a laser light source itself, or reduction in component costs, is demanded.

[0004] Further, in order to project emission light from a plurality of laser light sources onto an optical device such as a projector, the emission light needs to be substantially collimated by a microlens or the like in the laser light source itself.

[0005] In view of the above, as a structure of enhancing optical output power in a laser

light source itself and substantially collimating an emission light, for example, a structure as illustrated in Patent Document 1 is disclosed. In the structure of Patent Document 1, a semiconductor laser device having a plurality of light emitting points, i.e., a multi-emitter semiconductor laser device, is installed, and further, an emission light of the multi-emitter semiconductor laser device is substantially collimated using a microlens.

#### Prior Art Document

#### Patent Document

[0006] Patent Document 1: Japanese Patent Application Laid-Open No. 2015-153840

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#### Summary

#### Problem to be Solved by the Invention

[0007] In order to substantially collimate an emission light from a semiconductor laser device, a microlens needs to be arranged on an optical axis.

15 [0008] However, in a case where a semiconductor laser device and a microlens are mounted coplanarly on a substrate such as a stem, a lower half component in a fast axis direction (y-axis direction) of an emission light impinges upon a substrate for supporting a semiconductor laser, such as a stem, because a divergence angle of the emission light of the semiconductor laser device is large. In this case, optical output power is lost.

20 [0009] Therefore, for example, in a structure illustrated in Patent Document 1, a semiconductor laser device is arranged on a stem with an intermediation of a supporting member such as a block or a sub-mount, and further, a microlens for substantially collimating an emission light is arranged on a side surface of the block. Such arrangement realizes a structure allowing all emission light beams to be projected into the  
25 microlens so as to be substantially collimated.

[0010] In such a structure, arrangement of the semiconductor laser device needs to be adjusted in order to prevent loss of optical output power from the semiconductor laser device. Therefore, the degree of freedom in arrangement of the semiconductor laser device is hindered.

- 5 [0011] A technology disclosed in the specification of the subject application has been made in order to solve the problems as described above, and relates to a laser light source device capable of suppressing loss of optical output power from a semiconductor laser device, and to a method of manufacturing of a laser light source device while the degree of freedom in arrangement of the semiconductor laser device is secured.

10 Means to Solve the Problem

[0012] One aspect of a technology disclosed in the specification of the subject application includes a semiconductor laser device, and an optical element provided on an optical axis of an emission light that is emitted from the semiconductor laser device. The optical element separates a portion of a luminous flux of the emission light that is  
15 emitted from the semiconductor laser device and that is not separated in a fast axis direction from another portion so as to be separated in the fast axis direction.

[0013] Further, another aspect of a technology disclosed in the specification of the subject application includes preparing a semiconductor laser device, providing an optical  
20 laser device, separating, with use of the optical element, a portion of a luminous flux of the emission light that is emitted from the semiconductor laser device and that is not separated in a fast axis direction from another portion so as to be separated in the fast axis direction, making the optical element have a structure in which lens parts are combined together, the lens parts being obtained by dividing one lens into two along an optical axis  
25 direction of the semiconductor laser device and a direction orthogonal to the optical axis

direction of the semiconductor laser device, defining, as a first lens part, one of the lens parts arranged on a side closer to the semiconductor laser device before the division, defining, as a second lens part and a third lens part, the lens parts arranged on a side farther from the semiconductor laser device before the division, processing a surface of the first lens part that extends along the optical axis of the semiconductor laser device into a first inclined surface that is inclined with respect to the optical axis of the semiconductor laser device, processing a portion of a surface of the second lens part that extends along the optical axis of the semiconductor laser device and that is formed by the division into a second inclined surface that is parallel to the first inclined surface, arranging the first lens part at a position where the first inclined surface approaches closer to the optical axis of the semiconductor laser device as the first inclined surface is more distant from the semiconductor laser device, arranging the third lens part, on the optical axis of the semiconductor laser device, at a position more distant from the semiconductor laser device than the first lens part, and arranging the second lens part at a position where a surface of the third lens part that extends along the optical axis of the semiconductor laser device and that is opposite to a surface formed by the division and a surface of the second lens part that extends along the optical axis of the semiconductor laser device and that is opposite to a surface formed by the division are brought adjacent to each other.

#### Effects of the Invention

[0014] One aspect of the technology disclosed in the specification of the subject application includes a semiconductor laser device, and an optical element provided on an optical axis of an emission light that is emitted from the semiconductor laser device, in which the optical element separates a portion of a luminous flux of the emission light that is emitted from the semiconductor laser device and that is not separated in a fast axis direction from another portion so as to be separated in the fast axis direction. According

to such a configuration, loss of optical output power from a semiconductor laser device can be suppressed while the degree of freedom in arrangement of the semiconductor laser device is secured.

[0015] Further, another aspect of the technology disclosed in the specification of the subject application includes preparing a semiconductor laser device, providing an optical element on an optical axis of an emission light that is emitted from the semiconductor laser device, separating, with use of the optical element, a portion of a luminous flux of the emission light that is emitted from the semiconductor laser device and that is not separated in a fast axis direction from another portion so as to be separated in the fast axis direction, making the optical element have a structure in which lens parts are combined together, the lens parts being obtained by dividing one lens into two along an optical axis direction of the semiconductor laser device and a direction orthogonal to the optical axis direction of the semiconductor laser device, defining, as a first lens part, one of the lens parts arranged on a side closer to the semiconductor laser device before the division, defining, as a second lens part and a third lens part, the lens parts arranged on a side farther from the semiconductor laser device before the division, processing a surface of the first lens part that extends along the optical axis of the semiconductor laser device into a first inclined surface that is inclined with respect to the optical axis of the semiconductor laser device, processing a portion of a surface of the second lens part that extends along the optical axis of the semiconductor laser device and that is formed by the division into a second inclined surface that is parallel to the first inclined surface, arranging the first lens part at a position where the first inclined surface approaches closer to the optical axis of the semiconductor laser device as the first inclined surface is more distant from the semiconductor laser device, arranging the third lens part, on the optical axis of the semiconductor laser device, at a position more distant from the semiconductor

laser device than the first lens part, and arranging the second lens part at a position where a surface of the third lens part that extends along the optical axis of the semiconductor laser device and that is opposite to a surface formed by the division and a surface of the second lens part that extends along the optical axis of the semiconductor laser device and that is opposite to a surface formed by the division are brought adjacent to each other. According to such a configuration, loss of optical output power from a semiconductor laser device can be suppressed while the degree of freedom in arrangement of the semiconductor laser device is secured.

[0016] An object, features, aspects, and advantages relating to the technology disclosed in the specification of the subject application become more obvious with the following detailed description and the attached drawings.

#### Brief Description of Drawings

[0017] FIG. 1 is a view schematically illustrating a configuration for implementing a laser light source device according to an embodiment.

FIG. 2 is a view illustrating optical paths of an emission light in a fast axis direction of the laser light source device according to the embodiment.

FIG. 3 is a view illustrating a configuration of an optical element according to the embodiment.

FIG. 4 is a view illustrating a configuration of the optical element according to the embodiment.

FIG. 5 is a view illustrating a configuration of the optical element according to the embodiment.

FIG. 6 is a view illustrating a structure of a sub-mount according to the embodiment.

FIG. 7 is a view illustrating a structure of the sub-mount according to the embodiment.

#### Description of Embodiment

5 [0018] Now, description is given of an embodiment with reference to the attached drawings.

[0019] Note that, the drawings are schematically illustrated, and an interrelationship between the size and the position of an image illustrated in each different drawing is not necessarily illustrated to be accurate but is changeable as appropriate.

10 [0020] Further, in the description illustrated below, similar components are denoted by the same reference symbols in illustration, and the term and the function thereof are assumed to be similar as well. Accordingly, detailed description of such components may be omitted.

[0021] Further, in the description given below, even in a case where terms denoting  
15 particular positions and directions, such as “up,” “down,” “side,” “bottom,” “front,” and “back,” are used, such terms are used for the convenience sake to facilitate understanding of details of the embodiment, and are not related to directions in actual implementation.

[0022] <Embodiment>

Now, description is given of a laser light source device and a method of  
20 manufacturing a laser light source device according to this embodiment.

[0023] <Configuration of Laser Light Source Device>

FIG. 1 is a view schematically illustrating a configuration for implementing a  
laser light source device according to this embodiment. As illustrated in FIG. 1, the  
laser light source device includes a stem 1, a semiconductor laser device 2 that is mounted  
25 to the stem 1 and that has at least one light emitting point, and an optical element 3 that is

mounted to the stem 1 and that substantially collimates an emission light of the semiconductor laser device 2.

[0024] The stem 1 is formed into a plate-like shape, and is, for example, a stem base of a metallic material obtained by depositing Au plating and a metallized pattern on a surface of a highly thermally conductive material such as Cu. The stem 1 has a role of  
5 fixing the semiconductor laser device 2 and the optical element 3, and of dissipating heat generated in the semiconductor laser device 2 to a cooling member (herein not shown) below the stem 1.

[0025] The semiconductor laser device 2 is, for example, a laser diode in which at least  
10 one light emitting point is arranged on an end surface of a semiconductor chip containing GaAs, AlGaIn, or the like. From each light emitting point in the semiconductor laser device 2, a laser light is emitted along an optical axis that is perpendicular to the chip end surface and that is parallel to a chip main surface.

[0026] The optical element 3 includes a microlens 3A, a microlens 3B, and a microlens  
15 3C. The optical element 3 has a function of substantially collimating a laser light. Further, the optical element 3 may have a function of a prism.

[0027] The optical element 3 is arranged on an optical axis of an emission light emitted from the semiconductor laser device 2. Further, the optical element 3 separates a portion of a luminous flux of an emission light that is emitted from the semiconductor laser  
20 device 2 and that is not separated in a fast axis direction from another portion so as to be separated in the fast axis direction. As a method of separation, for example, reflection and refraction are assumable.

[0028] In joining of the stem 1 and the semiconductor laser device 2, for example, AuSn solder excellent in reliability and thermal conductivity is used as solder to be used  
25 at the time of the joining.

[0029] FIG. 2 is a view illustrating optical paths of an emission light in the fast axis direction of the laser light source device.

[0030] In the fast axis direction, a divergence angle (total angle) of an emission light from the semiconductor laser device 2 is approximately  $80^\circ$ . Therefore, usually, in a case where the semiconductor laser device 2 is directly mounted to the stem 1, a lower-half component of an emission light impinges upon the stem 1 to lose its optical output power.

[0031] However, as illustrated in FIG. 2, the laser light source device according to this embodiment includes the microlens 3A having a trapezoidal shape in the vicinity of a light emitting point of the semiconductor laser device 2. Owing to such a structure, a lower-half component of an emission light from the semiconductor laser device 2 in a fast axis direction being a vertical direction of FIG. 2, i.e., an emission light 11, is reflected by a reflection surface 100 of the trapezoidal microlens 3A toward a side opposite to the direction in which the stem 1 is arranged. In other words, the emission light 11 that has a component diverging toward the stem 1 side is converted into a light that has a component diverging toward a side opposite to the stem 1 side.

[0032] Here, the reflection surface 100 is such an inclined surface as to approach closer to the optical axis of the semiconductor laser device 2 as the surface is more distant from the semiconductor laser device 2. The reflection surface 100 illustrated in FIG. 2 comes in contact with the stem 1 on its end portion on a side closer to the semiconductor laser device 2. Further, the reflection surface 100 is out of contact with the stem 1 on its end portion on a side farther from the semiconductor laser device 2.

[0033] Further, the microlens 3B provided on an upper surface of the stem 1 and the microlens 3C provided on an upper surface of the microlens 3B are arranged behind the optical paths of the trapezoidal microlens 3A. Owing to such a structure, the emission

light 11 reflected on the reflection surface 100 is further reflected on a reflection surface 101 of the microlens 3C, and is then substantially collimated by an optical effect surface 102 of the microlens 3C for substantially collimating light. Here, the reflection surface 101 is a surface parallel to the reflection surface 100.

5 [0034] Such reflection of an emission light as described above enables suppression of light loss due to impingement of the emission light upon the stem 1, and thus extractable substantially collimated light can be increased.

[0035] Note that, an upper-half component of an emission light from the semiconductor laser device 2 in the fast axis direction, i.e., an emission light 10, is  
10 substantially collimated by an optical effect surface 103 of the microlens 3B for substantially collimating light.

[0036] Owing to such a structure, even in a case where the semiconductor laser device 2 and an optical element such as a microlens are arranged coplanarly, loss of optical output power of an emission light can be suppressed and extractable substantially  
15 collimated light can be increased.

[0037] FIG. 3, FIG. 4, and FIG. 5 are each a view illustrating a configuration of the optical element 3. With reference to FIG. 3, FIG. 4, and FIG. 5, description is given of a configuration of the optical element 3 obtained by combining together the microlens 3A, the microlens 3B, and the microlens 3C that are illustrated in FIG. 1 and FIG. 2.

20 [0038] For example, as illustrated in FIG. 3, one microlens is cut at the positions of the dotted lines. Specifically, one microlens is divided into two along an optical axis direction of the semiconductor laser device 2 (z-axis direction) and a direction orthogonal to the optical axis direction of the semiconductor laser device 2 (y-axis direction in FIG. 3). Further, a surface of a part A that extends along the optical axis of the  
25 semiconductor laser device 2 is cut so as to have inclination with respect to the optical

axis of the semiconductor laser device 2. With this, the reflection surface 100 is formed. Then, a portion of a surface of a part C that extends along the optical axis of the semiconductor laser device 2 and that is formed by the division is cut so as to have inclination with respect to the optical axis of the semiconductor laser device 2. With this, the reflection surface 101 is formed. Then, as illustrated in FIG. 4, the cut part A, part B, and part C are separated apart.

[0039] Further, as illustrated in FIG. 5, the cut part A, part B, and part C are combined together, thus enabling construction of the optical element 3. Specifically, the part A is arranged at a position where the reflection surface 100 approaches closer to the optical axis of the semiconductor laser device 2 as the reflection surface 100 is more distant from the semiconductor laser device 2. Then, the part B is arranged, on the optical axis of the semiconductor laser device 2, at a position more distant from the semiconductor laser device 2 than the part A. Then, the part C is arranged at a position where a surface of the part B that extends along the optical axis of the semiconductor laser device 2 and that is opposite to the surface formed by the division and a surface of the part C that extends along the optical axis of the semiconductor laser device 2 and that is opposite to the surface formed by the division are brought adjacent to each other.

[0040] According to such a method, the number of microlenses used to manufacture the optical element 3 suffices to be one, and hence component costs can be reduced.

[0041] Further, as for bonding at the time of combining together the microlens 3A, the microlens 3B, and the microlens 3C, for example, an epoxy-based adhesive may be used. In a case of using an epoxy-based resin, joining may be carried out by temporarily curing a resin with ultraviolet light irradiation immediately after bonding, and then by curing the resin with heat through heat treatment.

[0042] Note that, a sub-mount 4 may be mounted between the stem 1 and the

semiconductor laser device 2 as necessary. In general, a sub-mount has an electric insulation function and a heat conduction function.

[0043] FIG. 6 and FIG. 7 are each a view illustrating a structure of the sub-mount 4. As illustrated in FIG. 6 and FIG. 7, the sub-mount 4 has an electrical insulator 4A having a flat plate-like shape, a plurality of metallized patterns 4B and metallized patterns 4C that are formed in a surface of the electrical insulator 4A, and a metallized pattern 4D that is formed across an entire back surface of the electrical insulator 4A. As the electrical insulator 4A, for example, SiC, AlN, or the like, which has high thermal conductivity, is used.

10 [0044] Further, the metallized pattern 4B and the semiconductor laser device 2 in the sub-mount 4 are joined using solder. The metallized pattern 4C of the sub-mount 4 and a drive electrode of each semiconductor laser device 2 are electrically connected through contact bonding with ultrasonic vibration, for example, using an electrically conductive wire 5 such as Au.

15 [0045] Note that, the metallized pattern 4D is formed not for the purpose of power supply. The metallized pattern 4D is provided for the purpose of suppressing deflection of the sub-mount that may be generated due to difference between a linear expansion coefficient of the electrical insulator 4A and a linear expansion coefficient of the metallized pattern 4B, or due to difference between a linear expansion coefficient of the electrical insulator 4A and a linear expansion coefficient of the metallized pattern 4C.

[0046] When the sub-mount 4 is mounted, a mounting surface of the semiconductor laser device 2 and a mounting surface of the optical element 3 are no longer coplanar. However, in a case where a mounting surface of the sub-mount 4 and a mounting surface of the optical element 3 are coplanar, the thickness of the sub-mount 4 is, for example, 20 300  $\mu\text{m}$  or more and 600  $\mu\text{m}$  or less. From the above, in order to substantially collimate 25

all emission light beams in the fast axis direction of the semiconductor laser device 2, a structure as the optical element 3 needs to be provided after all.

[0047] <Effects Generated by Embodiment Described Above>

Now, effects generated by the embodiment described above are illustrated.

5 Note that, such effects are described below based on specific configurations illustrated in the embodiment described above. However, another specific configuration illustrated in the specification of the subject application may substitute as long as similar effects are generated.

[0048] According to the embodiment described above, the laser light source device  
10 includes the semiconductor laser device 2 and the optical element 3. Further, the optical element 3 is provided on an optical axis of an emission light emitted from the semiconductor laser device 2. Further, the optical element 3 separates a portion of a luminous flux of an emission light that is emitted from the semiconductor laser device 2 and that is not separated in the fast axis direction from another portion so as to be  
15 separated in the fast axis direction.

[0049] According to such a configuration, in a case where loss of optical output power may be generated due to impingement of, upon an obstruction or the like, a portion of a luminous flux of an emission light emitted from the semiconductor laser device 2, for example, generation of such loss of optical output power due to impingement upon an  
20 obstruction or the like can be suppressed by, for example, separating the emission light in the fast axis direction from another portion. Further, arrangement of the semiconductor laser device need not be adjusted, and therefore the degree of freedom in arrangement of the semiconductor laser device can be secured.

[0050] Note that, other configurations illustrated in the specification of the subject  
25 application excluding the configurations above may be omitted as appropriate. That is,

the effects described above can be generated only with the configurations above.

[0051] However, also in a case where at least one of other configurations illustrated in the specification of the subject application is added to the configurations described above as appropriate, that is, also in a case where other configurations omitted as the configurations described above but illustrated in the specification of the subject application are added to the configurations described above, the effects described above can be similarly generated.

[0052] Further, according to the embodiment described above, an emission light emitted from the semiconductor laser device has a component diverging in the fast axis direction. Here, a light that is contained in an emission light from the semiconductor laser device 2 and that has a component diverging in a first direction within the fast axis direction is defined as a first emission light. Further, a light that is contained in an emission light from the semiconductor laser device 2 and that has a component diverging in a second direction being a direction opposite to the first direction within the fast axis direction is defined as a second emission light. Here, the emission light 11 corresponds to the first emission light. Further, the emission light 10 corresponds to the second emission light. Further, the optical element 3 converts the emission light 11 into a light that has a component diverging in the second direction within the fast axis direction. According to such a configuration, the emission light 11 that has a component diverging in the first direction, which is contained in an emission light that is emitted from the semiconductor laser device 2 and that has a component diverging in the fast axis direction, can be converted into a light that has a component diverging in the second direction opposite to the first direction. Accordingly, generation of loss of optical output power due to impingement of the emission light 11 upon an obstruction present in the first direction can be suppressed.

[0053] Further, according to the embodiment described above, the optical element 3 emits light beams parallel to each other by refracting the emission light 10 and the converted emission light 11. According to such a configuration, an emission light that is emitted from the semiconductor laser device 2 and that has a component diverging in the fast axis direction can be converted into light beams parallel to each other to be emitted.

[0054] Further, according to the embodiment described above, the optical element 3 has such an inclined surface as to approach closer to the optical axis of the semiconductor laser device 2 as the surface is more distant from the semiconductor laser device 2. Here, the reflection surface 100 corresponds to the inclined surface. According to such a configuration, the emission light 11 that has a component diverging toward the stem 1 side can be reflected toward a side opposite to the stem 1 side. Accordingly, generation of loss of optical output power due to impingement of the emission light 11 upon the stem 1 can be suppressed.

[0055] Further, according to the embodiment described above, the laser light source device includes a flat plate-like flat plate member. Here, the stem 1 corresponds to the flat plate member. Further, the optical element 3 is provided on an upper surface of the stem 1. The emission light 11 is a light that is contained in an emission light from the semiconductor laser device 2 and that has a component diverging toward the stem 1 side in the fast axis direction. Further, the emission light 10 is a light that is contained in an emission light from the semiconductor laser device 2 and that has a component diverging toward a side opposite to the stem 1 side in the fast axis direction. Further, the optical element 3 converts the emission light 11 into a light that has a component diverging toward a side opposite to the stem 1 side with respect to the optical axis. According to such a configuration, the emission light 11 that has a component diverging toward the stem 1 side, which is contained in an emission light that is emitted from the

semiconductor laser device 2 and that has a component diverging in the fast axis direction, can be converted into a light that has a component diverging toward a side opposite to the stem 1 side. Accordingly, generation of loss of optical output power due to impingement of the emission light 11 upon the stem 1 can be suppressed.

5 [0056] Further, according to the embodiment described above, the optical element 3 reflects the emission light 11 toward a side opposite to the stem 1 side. According to such a configuration, the emission light 11 that has a component diverging toward the stem 1 side, which is contained in an emission light that is emitted from the semiconductor laser device 2 and that has a component diverging in the fast axis direction,  
10 can be reflected toward a side opposite to the stem 1 side. Accordingly, generation of loss of optical output power due to impingement of the emission light 11 upon the stem 1 can be suppressed.

[0057] Further, according to the embodiment described above, the semiconductor laser device 2 is provided on an upper surface of the stem 1. According to such a  
15 configuration, loss of optical output power from the semiconductor laser device 2 can be suppressed without the necessity of a member for supporting the semiconductor laser device 2, such as a block or a sub-mount. Specifically, even in a case where the semiconductor laser device 2 and the optical element 3 are arranged coplanarly, loss of a light that has a component diverging toward the stem 1 side in the fast axis direction of  
20 the semiconductor laser device 2 can be suppressed. Further, the number of components for constructing the device is not increased, and therefore manufacturing costs can be reduced. Further, the manufacturing process can be simplified. Further, in a case where a cooling device or the like is arranged on a lower surface of the stem 1 to thereby cool the semiconductor laser device 2, thermal resistance until the reach to the  
25 semiconductor laser device 2 can be reduced. Therefore, optical output power

characteristics can be enhanced. Further, reliability of the device can be maintained.

[0058] Further, according to the embodiment described above, the laser light source device includes the sub-mount 4 provided on an upper surface of the stem 1. Further, the semiconductor laser device 2 is provided on an upper surface of the sub-mount 4.

5 According to such a configuration, such a case can also be assumed where a mounting surface of the semiconductor laser device 2 and a mounting surface of the optical element 3 are not coplanar. Further, even in a case of such a structure, generation of loss of optical output power due to impingement upon an obstruction or the like can be suppressed, for example, because an emission light emitted from the semiconductor laser  
10 device 2 is appropriately separated in the fast axis direction by the optical element 3. Further, the thickness of the sub-mount 4 can be assumed to be, for example, 300  $\mu\text{m}$  or more and 600  $\mu\text{m}$  or less, and hence heat dissipation of the semiconductor laser device 2 can be maintained.

[0059] Further, according to the embodiment described above, the optical element 3  
15 has a structure in which lenses decomposed from one lens are combined together. According to such a configuration, the number of microlenses used to manufacture the optical element 3 suffices to be one, and hence component costs can be reduced.

[0060] Further, according to the embodiment described above, the optical element 3 has a function of substantially collimating a laser light, or a function of a prism.  
20 According to such a configuration, an emission light that is emitted from the semiconductor laser device 2 and that has a component diverging in the fast axis direction can be converted into light beams parallel to each other to be emitted.

[0061] Further, according to the embodiment described above, in the method of manufacturing a laser light source device, the semiconductor laser device 2 is prepared.  
25 Then, the optical element 3 is provided on the optical axis of an emission light emitted

from the semiconductor laser device 2. Here, the optical element 3 separates a portion of a luminous flux of an emission light that is emitted from the semiconductor laser device 2 and that is not separated in the fast axis direction from another portion so as to be separated in the fast axis direction. Further, the optical element 3 has a structure in which lens parts obtained by dividing one lens into two along an optical axis direction of the semiconductor laser device 2 and a direction orthogonal to the optical axis direction of the semiconductor laser device 2 are combined together. Here, one of the lens parts arranged on a side closer to the semiconductor laser device 2 before the division is defined as a first lens part. Further, the lens parts arranged on a side farther from the semiconductor laser device 2 before the division are defined as a second lens part and a third lens part. Note that, the part A corresponds to the first lens part. Further, the part B corresponds to the third lens part. Further, the part C corresponds to the second lens part. Further, a surface of the part A that extends along the optical axis of the semiconductor laser device 2 is processed into a first inclined surface that is inclined with respect to the optical axis of the semiconductor laser device 2. Note that, the reflection surface 100 corresponds to the first inclined surface. Then, a portion of a surface of the part C that extends along the optical axis of the semiconductor laser device 2 and that is formed by the division is processed into a second inclined surface that is parallel to the reflection surface 100. Note that, the reflection surface 101 corresponds to the second inclined surface. Then, the part A is arranged at a position where the reflection surface 100 approaches closer to the optical axis of the semiconductor laser device 2 as the reflection surface 100 is more distant from the semiconductor laser device 2. Then, the part B is arranged, on the optical axis of the semiconductor laser device 2, at a position more distant from the semiconductor laser device 2 than the part A. Then, the part C is arranged at a position where a surface of the part B that extends along the optical axis of

the semiconductor laser device 2 and that is opposite to the surface formed by the division and a surface of the part C that extends along the optical axis of the semiconductor laser device 2 and that is opposite to the surface formed by the division are brought adjacent to each other.

5 [0062] According to such a configuration, loss of optical output power from the semiconductor laser device 2 can be suppressed while the degree of freedom in arrangement of the semiconductor laser device 2 is secured. Further, the number of microlenses used to manufacture the optical element 3 suffices to be one, and hence component costs can be reduced.

10 [0063] Note that, other configurations illustrated in the specification of the subject application excluding the configurations above may be omitted as appropriate. That is, the effects described above can be generated only with the configurations above.

[0064] However, also in a case where at least one of other configurations illustrated in the specification of the subject application is added to the configurations described above  
15 as appropriate, that is, also in a case where other configurations omitted as the configurations described above but illustrated in the specification of the subject application are added to the configurations described above, the effects described above can be similarly generated.

[0065] Further, unless special limitation is imposed, the order of implementing each  
20 processing may be changed.

[0066] <Modified Example in Embodiment Described Above>

In the embodiment described above, material quality, a material, dimensions, a shape, a relative arrangement relationship, a condition for implementation, or the like of each component may also be described, which however are in all aspects illustrative and  
25 are not to be limited to such described in the specification of the subject application.

[0067] Accordingly, unillustrated numerous modified examples are assumable within the scope of the technology disclosed in the specification of the subject application. For example, the case of modifying at least one component, the case of adding at least one component, or the case of omitting at least one component is encompassed.

5 [0068] Further, unless there arises a contradiction, concerning a component whose number to be provided has been described to be “one” in the embodiment described above, “one or more” of the components may be provided.

[0069] Further, each component is a conceptual unit. A case where one component is made of a plurality of structural objects, a case where one component corresponds to a part of a certain structural object, and a case where a plurality of components are provided  
10 in one structural object are encompassed.

[0070] Further, as long as the same function is exhibited, each component encompasses a structural object having another structure or shape.

[0071] Further, the description in the specification of the subject application is to be  
15 referred to for the sake of every object relating to the subject technology, any of which is not to be acknowledged as a conventional technology.

[0072] Further, in the embodiment described above, in a case where a material name or the like is described without particular specification, a material obtained by adding another additive to the material, such as an alloy, for example, is encompassed unless  
20 there arises a contradiction.

#### Explanation of Reference Signs

[0073] 1 stem, 2 semiconductor laser device, 3 optical element, 3A, 3B, 3C microlens, 4 sub-mount, 4A electrical insulator, 4B, 4C, 4D metallized pattern, 5 electrically  
conductive wire, 10, 11 emission light, 100, 101 reflection surface, 102, 103 optical effect  
25 surface, A, B, C part

## CLAIMS:

[Claim 1] A laser light source device comprising:

a semiconductor laser device; and

an optical element provided on an optical axis of an emission light that is  
5 emitted from the semiconductor laser device,

the semiconductor laser device and the optical element being provided  
coplanarly, wherein

the optical element separates, out of a luminous flux of the emission light that is  
emitted from the semiconductor laser device and that is not separated in a fast axis, a light  
10 that has a component expanding in a first direction within the fast axis as a first emission  
light, and a light that has a component expanding in a second direction being a direction  
opposite to the first direction with respect to the fast axis within the fast axis as a second  
emission light,

the optical element converts the first emission light into a light that has a  
15 component diverging in the second direction within the fast axis, and

the optical element emits light beams which are substantially collimated and  
parallel to each other by refracting the second emission light and the converted first  
emission light.

20 [Claim 2] The laser light source device according to claim 1, wherein the optical element  
has such an inclined surface as to approach closer to the optical axis of the semiconductor  
laser device as the inclined surface is more distant from the semiconductor laser device.

[Claim 3] The laser light source device according to claim 1 or 2, further comprising:

25 a flat plate member having a flat plate-like shape; and

a sub-mount that is provided on an upper surface of the flat plate member,  
wherein

the optical element is provided on the upper surface of the flat plate member,

the first emission light is a light that is contained in the emission light from the  
5 semiconductor laser device and that has a component diverging toward a side of the flat  
plate member in the fast axis direction,

the second emission light is a light that is contained in the emission light from  
the semiconductor laser device and that has a component diverging toward a side opposite  
to the side of the flat plate member in the fast axis direction,

10 the optical element converts the first emission light into a light that has a  
component diverging toward a side opposite to the side of the flat plate member with  
respect to the optical axis, and

the semiconductor laser device is provided on an upper surface of the  
sub-mount.

15

[Claim 4] The laser light source device according to any one of claims 1 to 3, wherein

the optical element has a structure in which lens parts are combined together,  
the lens parts being obtained by dividing one lens into two along an optical axis direction  
of the semiconductor laser device and a direction orthogonal to the optical axis direction  
20 of the semiconductor laser device,

one of the lens parts arranged on a side closer to the semiconductor laser device  
before the division is defined as a first lens part,

the lens parts arranged on a side farther from the semiconductor laser device  
before the division are defined as a second lens part and a third lens part,

25 a surface of the first lens part that extends along the optical axis of the

semiconductor laser device is processed into a first inclined surface that is inclined with respect to the optical axis of the semiconductor laser device,

a portion of a surface of the second lens part that extends along the optical axis of the semiconductor laser device and that is formed by the division is processed into a  
5 second inclined surface that is parallel to the first inclined surface,

the first lens part is arranged at a position where the first inclined surface approaches closer to the optical axis of the semiconductor laser device as the first inclined surface is more distant from the semiconductor laser device,

the third lens part is arranged, on the optical axis of the semiconductor laser  
10 device, at a position more distant from the semiconductor laser device than the first lens part, and

the second lens part is arranged at a position where a surface of the third lens part that extends along the optical axis of the semiconductor laser device and that is opposite to a surface formed by the division and a surface of the second lens part that  
15 extends along the optical axis of the semiconductor laser device and that is opposite to a surface formed by the division are brought adjacent to each other.

[Claim 5] The laser light source device according to any one of claims 1 to 4, wherein the optical element has a function of substantially collimating a laser light or a function of a  
20 prism.

[Claim 6] A method of manufacturing a laser light source device, the method comprising:  
preparing a semiconductor laser device;  
providing an optical element on an optical axis of an emission light that is  
25 emitted from the semiconductor laser device;

separating, with use of the optical element, a portion of a luminous flux of the emission light that is emitted from the semiconductor laser device and that is not separated in a fast axis direction from another portion so as to be separated in the fast axis direction;

5 making the optical element have a structure in which lens parts are combined together, the lens parts being obtained by dividing one lens into two along an optical axis direction of the semiconductor laser device and a direction orthogonal to the optical axis direction of the semiconductor laser device;

defining, as a first lens part, one of the lens parts arranged on a side closer to  
10 the semiconductor laser device before the division;

defining, as a second lens part and a third lens part, the lens parts arranged on a side farther from the semiconductor laser device before the division;

processing a surface of the first lens part that extends along the optical axis of the semiconductor laser device into a first inclined surface that is inclined with respect to  
15 the optical axis of the semiconductor laser device;

processing a portion of a surface of the second lens part that extends along the optical axis of the semiconductor laser device and that is formed by the division into a second inclined surface that is parallel to the first inclined surface;

arranging the first lens part at a position where the first inclined surface  
20 approaches closer to the optical axis of the semiconductor laser device as the first inclined surface is more distant from the semiconductor laser device;

arranging the third lens part, on the optical axis of the semiconductor laser device, at a position more distant from the semiconductor laser device than the first lens part; and

25 arranging the second lens part at a position where a surface of the third lens part

that extends along the optical axis of the semiconductor laser device and that is opposite to a surface formed by the division and a surface of the second lens part that extends along the optical axis of the semiconductor laser device and that is opposite to a surface formed by the division are brought adjacent to each other.

5

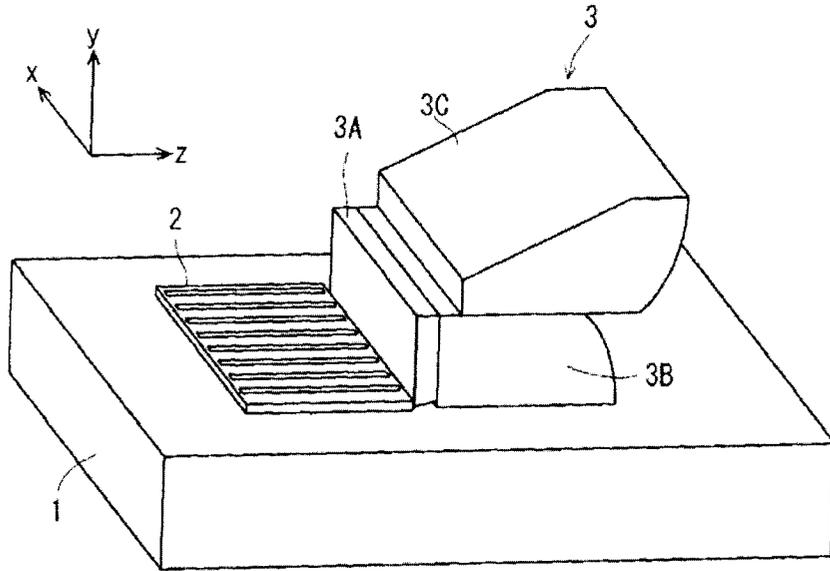


Fig. 1

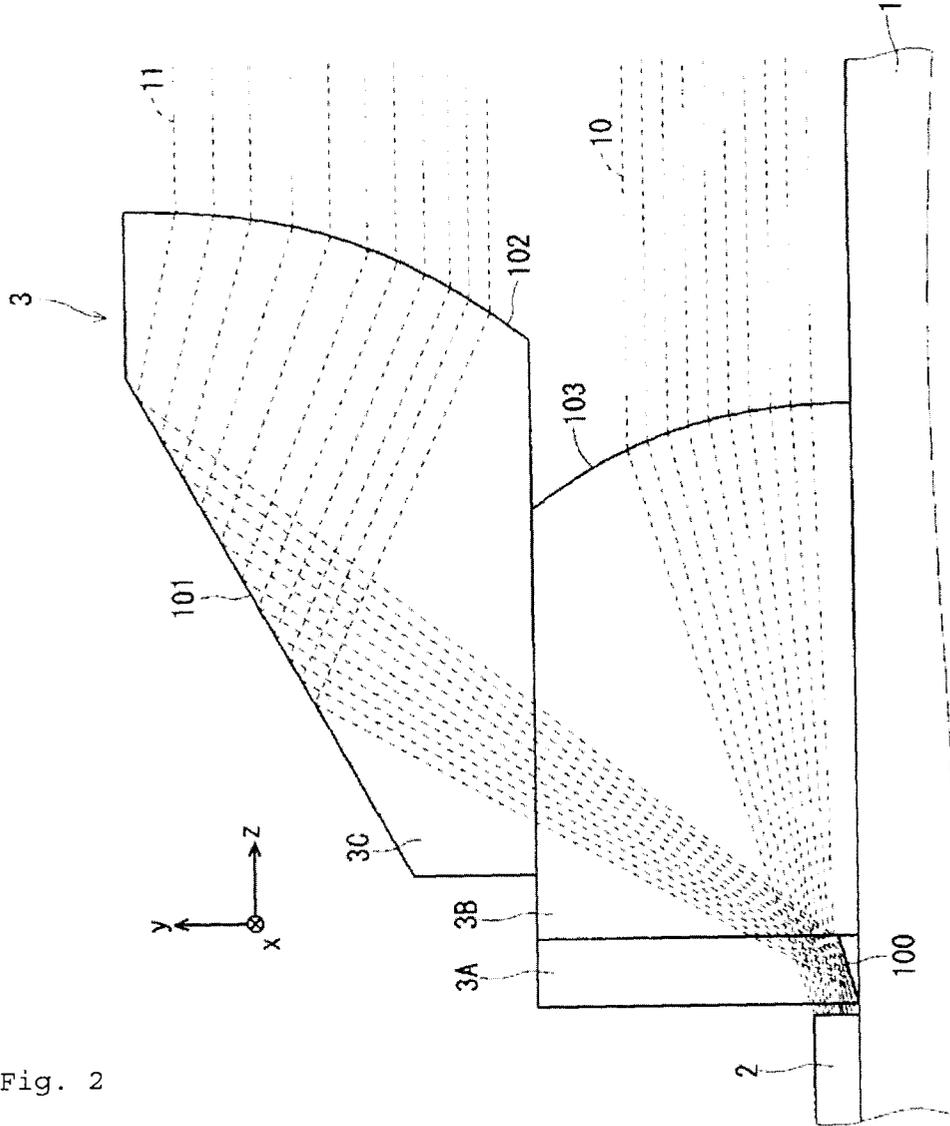


Fig. 2

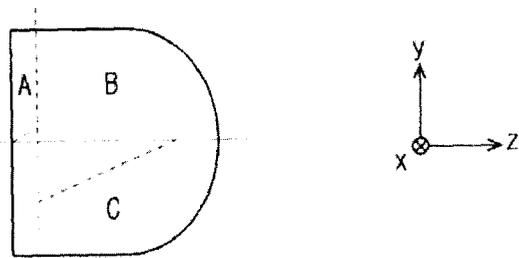


Fig. 3

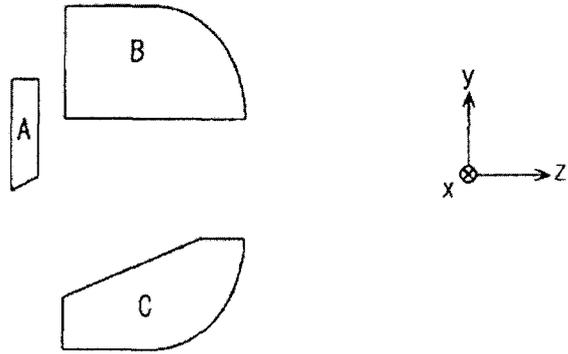


Fig. 4

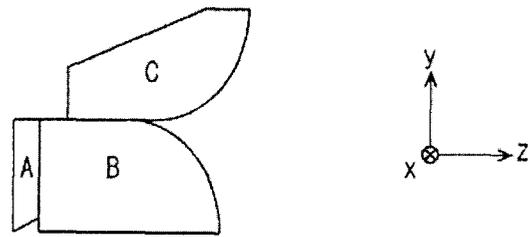


Fig. 5

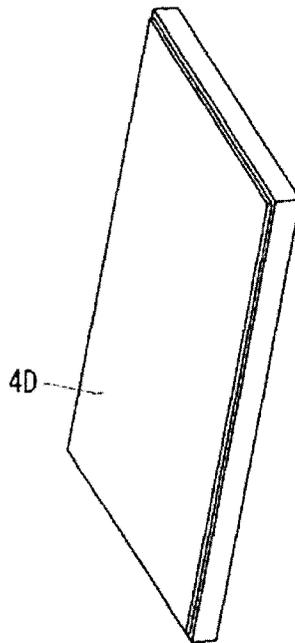


Fig. 6

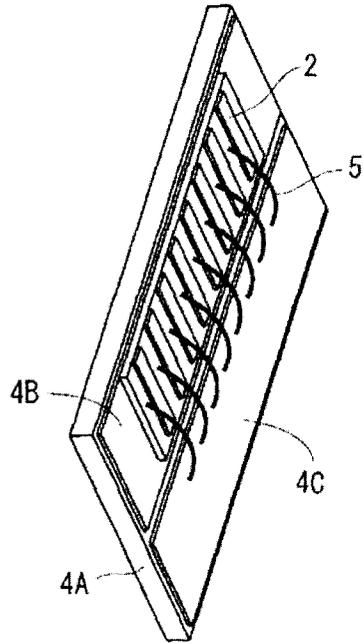


Fig. 7

